H223-S10-AAP1

High Density Server - 2U 3-Node UP 6-Bay E1.S Gen4 NVMe













Key Features

- 2U 3-node front access server system
- Single 5th/4th Gen Intel® Xeon® Scalable Processors per node
- Single Intel® Xeon® CPU Max Series per node
- 8-Channel DDR5 RDIMM, 8 x DIMMs per node
- Dual ROM Architecture
- 2 x CMC ports
- 6 x 9.5mm E1.S Gen4 NVMe hot-swap bays
- 3 x M.2 slots with SATA interface
- 6 x FHHL PCIe Gen5 x16 slots
- 3 x LP PCIe Gen5 x16 slots
- 3 x LP PCIe Gen5 x8 slots
- 1+1 3000W 80 PLUS Titanium redundant power supplies

Applications

High-Performance Computing Server, High Converged Server, Servers for Hybrid/Private Cloud, Edge Server...

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Dimensions Motherboard	2U 3-Node - Front access (W447.8 x H87.5 x D500 mm) MS13-HD0	PCIe Expansion Slots	6 x FHHL PCIe Gen5 x16 3 x LP PCIe Gen5 x16 3 x LP PCIe Gen5 x8	
CPU	5th Generation Intel® Xeon® Scalable Processors 4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series	I/O Ports	Front: 2 x CMC ports, 1 x CMC status LED, 3 x USB 3.2 Gen1, 3 x Mini-DP	
	Single processor per node - With 1 x PCle card per node at 35°C ambient, TDP up to 350W	Backplane Board	PCIe Gen4 x4	
	 With 2 x PCle cards per node at 30°C ambient, TDP up to 350W With 3 x PCle cards per node at 35°C ambient, TDP up to 300W 	ТРМ	1 x TPM header (SPI), Optional TPM2.0 kit: CTM010	
OS Compatibility	- With 4 x PCle cards per node at 30°C ambient, TDP up to 300W OS Support List	Power Supply	1+1 3000W 80 PLUS Titanium redundant power supplies AC Input: 100-240V	
Socket	3 x LGA 4677 (Socket E)		*The system power supply requires C19 power cord.	
Chipset	Intel® C741	System Management	ASPEED® AST2600 Baseboard Management Controller ASPEED® AST2520 Chassis Management Controller GIGABYTE Management Console web interface	
Memory	8-Channel DDR5 RDIMM, 24 x DIMMs			
	[5th Gen Intel Xeon] Up to 5600 MT/s [4th Gen Intel Xeon] Up to 4800 MT/s [Intel Xeon Max Series] Up to 4800 MT/s	System Fans	4 x 80x80x38mm	
LAN	2 x CMC Management LAN	Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)	
Video	Integrated in ASPEED [®] AST2600 x 3 - 3 x Mini-DP	Packaging Content	1 x H223-S10-AAP1 3 x CPU heatsinks 1 x Mini-DP to D-Sub cable 9 x Carriers 1 x L-shape Rail kit	
Storage	Front hot-swap: 6 x 9.5mm E1.S Gen4 NVMe Internal M.2:			
	3 x M.2 (2242/2260/2280/22110), SATA	Ordering Part Numbers	6NH223S10DR000ABP1*	
RAID	Onboard VROC key header	INGIIDEI 3		



